



Integrated Device Technology, Inc.
2975 Stender Way, Santa Clara, CA - 95054

PRODUCT/PROCESS CHANGE NOTICE (PCN)

PCN #: L0306-02 DATE: 7/3/03 Product Affected: Please see attachment for the product list Date Effective: October 2, 2003	MEANS OF DISTINGUISHING CHANGED DEVICES: <input type="checkbox"/> Product Mark <input type="checkbox"/> Back Mark <input checked="" type="checkbox"/> Date Code Prefix (Stepping) change. Please see attachment for details. <input type="checkbox"/> Other
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Contact: Bimla Paul Title: Quality Assurance Manager Phone #: (408)-654-6419 Fax #: (408)-492-8362 E-mail: bimla.paul@idt.com	Attachment: <input checked="" type="checkbox"/> Yes <input type="checkbox"/> No Samples: Available upon request.
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DESCRIPTION AND PURPOSE OF CHANGE:

<input type="checkbox"/> Die Technology	
<input type="checkbox"/> Wafer Fabrication Process	Selected Logic products will be transferred to IDT's wafer fab facility in Hillsboro, Oregon (Fab 4). There is no change in die technology.
<input type="checkbox"/> Assembly Process	
<input type="checkbox"/> Equipment	
<input type="checkbox"/> Material	Please see attachment for the product list and qualification data.
<input type="checkbox"/> Testing	
<input checked="" type="checkbox"/> Manufacturing Site	
<input type="checkbox"/> Data Sheet	
<input type="checkbox"/> Other	

RELIABILITY/QUALIFICATION SUMMARY:
Please see attachment for qualification data.

CUSTOMER ACKNOWLEDGMENT OF RECEIPT:
 IDT records indicate that you require written notification of this change. Please use the acknowledgement below or E-Mail to grant approval or request additional information. If IDT does not receive acknowledgement within 30 days of this notice it will be assumed that this change is acceptable.
 IDT reserves the right to ship either version manufactured after the process change effective date until the inventory on the earlier version has been depleted.

Customer: _____	<input type="checkbox"/> <i>Approval for shipments prior to effective date.</i>
Name/Date: _____	E-Mail Address: _____
Title: _____	Phone# /Fax# : _____

CUSTOMER COMMENTS: _____

IDT ACKNOWLEDGMENT OF RECEIPT:

RECD. BY: _____	DATE: _____
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PCN Type: Fab Site Change

Data Sheet Change: None

Detail of Change: Transfer existing qualified products to Hillsboro, Oregon Wafer Fab Facility (Fab 4). There is no change in die technology.

The following devices are affected by this change. All packages and speed grades are affected.

Part Number	Old Stepping	New Stepping (Fab 4)
IDTQS32XVH2245	Z	Z4
IDTQS34XVH2245	Z	Z4
IDTQS34XVH245	Z	Z4
IDTQS32X383	Z	Z4
IDTQS32XVH384	Z	Z4
IDTQS3306	Y, QA	Z

Conversion Schedule:

Die Revision

Sample Availability:

Production Shipment:

Z4 Stepping

Available

September 29, 2003

Z Stepping

Available

September 29, 2003



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Qualification Plans: Following reliability tests were performed per process and device families. The qualification results are as follow:

	Required Sample/ # Fails	Process Family Data	Z4 Device Family	Z Device Family
Operating Life Test: Dynamic 1000 hrs @ 125°C or equivalent	116/0	116/0	116/0	116/0
Temperature Cycling 500 Cycles -65°C to +150°C	45/0	45/0	N/A	N/A
Highly Accelerated Stress Test 100 hours	45/0	45/0	N/A	N/A
ESD Human Body Model	3/0	N/A	2500V (3/0)	3500V (3/0)
ESD Charged Device Model	3/0	N/A	1000V (3/0)	1000V (3/0)
Latch up: (Tested to 1.5X Vcc)	10/0	N/A	10/0	10/0

Characterization Data:

Characterization data is available upon request.